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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Appl. No. : 10/029,764**  
**Applicant : Wen-Kun Yang**  
**Filed : October 22, 2001**  
**Title : WAFER LEVEL PACKAGE FOR PRODUCING  
CHIP SIZE PACKAGES AND METHOD OF  
FABRICATING THE SAME**  
**Examiner : WILLIAMS, ALEXANDER O**  
**Docket No. : 6033.P075**

Honorable Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

In response to the Official Action mailed October 6, 2003, please amend the above-identified application as follows :

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims, which begin on page 15 of this paper.

**Amendments to the Abstract** begin on page 17 of this paper and include an attached replacement sheet.

**Remarks/Arguments** begin on page 19 of this paper.

**FAX RECEIVED**

**DEC 05 2003**

**TECHNOLOGY CENTER 2800**